

IEEE SPI 2023

27th IEEE Workshop on Signal and Power Integrity

May 07-10, 2023 - Aveiro, Portugal

Workshop Chairs

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CALL FOR PAPERS

Over the past two decades, the *IEEE Workshop on Signal and Power Integrity (SPI)* has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

In view of previous years success, the Committees are hardworking and keen on the 27th Edition which will be held as an in-person event in Aveiro, Portugal. The technical program will include both oral and poster sessions, and several prominent experts will be giving keynotes on areas of emerging interest.

Feel free to look into our website for further information about *IEEE SPI 2023*, as well as broadcast the workshop in your institution and to your fellow colleagues and students. It is a pleasure to invite you all to the 27th *IEEE Workshop on Signal and Power Integrity* and we look forward to your contribution and participation!

TOPICS

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/ sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- AI in electronics design

IMPORTANT DATES

- Full Paper Submission: **Jan 31st, 2023**
- Notification of Acceptance: **Mar 15th, 2023**
- Final Paper Submission: **Apr 5th, 2023**
- Student Awards Application: **Mar 31st, 2023**
- Early Bird Registration: **Apr 5th, 2023**
- Sponsors Registration: **Apr 5th, 2023**

SPONSORSHIPS

Companies interested in supporting the event are invited to join as Sponsors: **registrations are open!**

SUBMISSIONS ARE OPEN

- **Accepted papers** will be included in the workshop's program and submitted for inclusion into [IEEE Xplore®](#)
- Authors of the **best ranked accepted papers** will have the opportunity to submit an extended version of their work for publication in a special section of the [IEEE Transactions on Components, Packaging and Manufacturing Technology](#)

STUDENT AWARDS



Student Travel Grants



Best Student Paper